

Very Low Phase Noise Divider by 2^N

DS3738 - 2.1 March 1994

The SP8402 is a very low phase noise divider which divides by powers of two. The S0, S1, S2 data inputs select the division ratio in the range 2^1 to 2^8 . Special circuits techniques have been used to reduce the phase noise considerably below that produced by standard dividers. The data inputs are CMOS or TTL compatible.

The SP8402 is packaged in a 28 pin plastic SO package to be compatible with the SP8400 and SP8401 devices.

FEATURES

- Very low Phase Noise (Typically -155 to 160dBc/Hz at 1kHz offset)
- Supply Voltage 5V

ABSOLUTE MAXIMUM RATINGS

Supply Voltage 6.5V
Output Current 20mA
Storage Temperature Range -55°C to +125°C
Maximum Clock Input Voltage 2.5V p-p

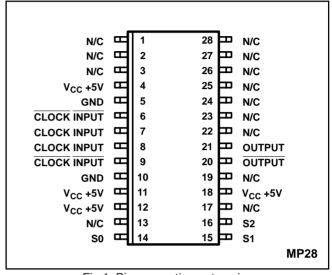


Fig.1 Pin connections - top view

ORDERING INFORMATION

SP8402 KG MPES (Commercial Grade)

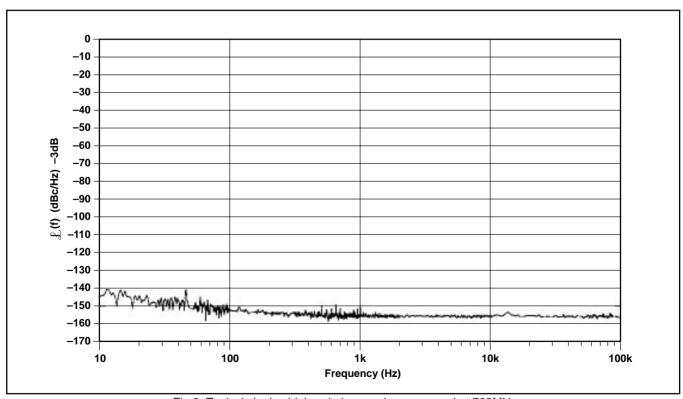


Fig.2 Typical single sideband phase noise measured at 768MHz

ELECTRICAL CHARACTERISTICS

Guaranteed over: Supply voltage V_{CC} = +4.75V to +5.25V Temperature T_{amb} = -10°C to +75°C Tested at +4.75V and +5.25V at T_{amb} = +25°C

Characteristic	Pin	Value			Units	Conditions	
Cital acteristic	FIII	Min.	Тур.	Max.		Conditions	
Supply current Output voltage swing Input sensitivity 200MHz to 1.5GHz	4, 11, 12, 18 20, 21 7, 8	82 320	92 410	102 140 (-4)	mA mV mV dBm	Output loaded with 300R See Fig.5 p-p @ 1.4GHz input ÷ 256 mode outputs loaded with 330R See Fig.5 RMS Sine wave into 50 Ohms (dBm equivalent) See Fig.3	
Data Inputs Logic high voltage Low low voltage Input current		2.2		0.8 180	V V μΑ	5V Data input voltage	

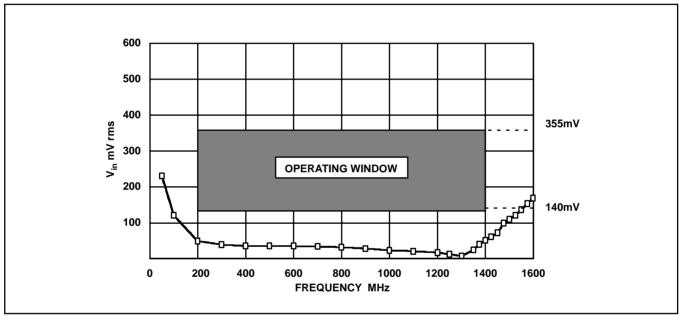


Fig.3 Typical input sensitivity

S0	S1	S2	DIVISION RATIO
L	L	L	2
Н	L	L	4
L	н	L	8
Н	н	L	16
L	L	Н	32
н	L	Н	64
L	н	Н	128
Н	н	Н	256

Fig.4 Truth table

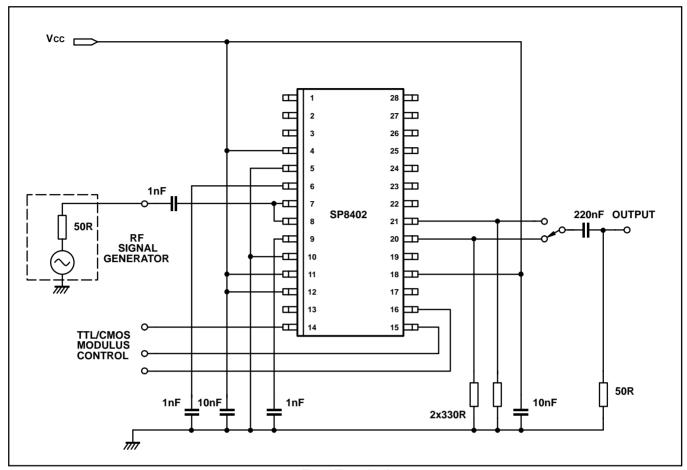


Fig.5 Test circuit

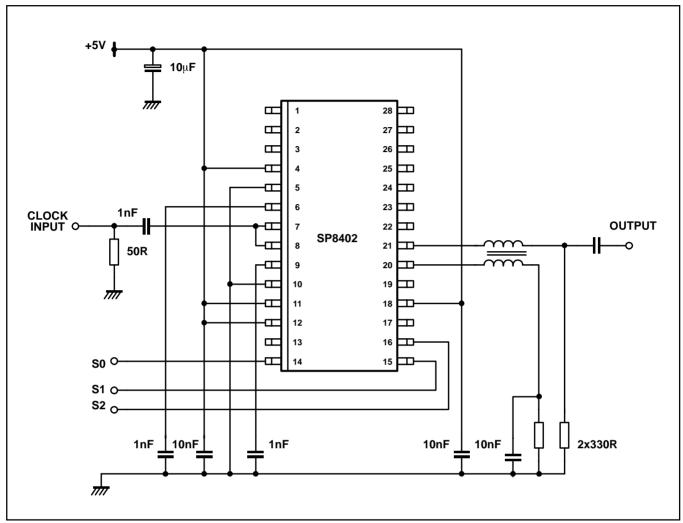
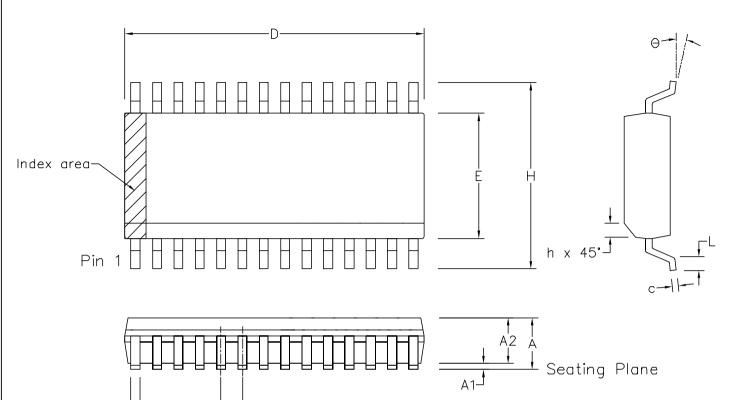


Fig.5 Typical application combining output to increase signal and retain low phase noise



	Contri	ol Dimer	nsions	Altern. Dimensions				
Symbol		millimet			in inches			
- j	MIN	Nominal	MAX		MIN	Nominal	MAX	
Α	2.35		2.65		0.093		0.104	
A1	0.10		0.30		0.004		0.012	
A2	2.25		2.35		0.089		0.092	
D	17.70		18.10		0.697		0.713	
Н	10.00		10.65		0.394		0.419	
Ε	7.40		7.60		0.291		0.299	
L	0.40		1.27		0.016		0.050	
е	1	.27 BS0).		0,050 BSC.			
Ь	0.33		0.51		0.013		0.020	
С	0.23		0.32		0.009		0.013	
Θ	0°		8°		0°		8"	
h	0.25		0.75		0.010		0.029	
	Pin features							
N	28							
Conforms to JEDEC MS-013AE Iss. C								

Notes:

- 1. The chamfer on the body is optional. If it not present, a visual index feature, e.g. a dot, must be located within the cross—hatched area.
- 2. Controlling dimension are in millimeters.

- 3. Dimension D do not include mould flash, protusion or gate burrs. These shall not exceed 0.006" per side.
 4. Dimension E1 do not include inter—lead flash or protusion. These shall not exceed 0.010" per side.
 5. Dimension b does not include dambar protusion/intrusion. Allowable dambar protusion shall be 0.004" total in excess of b dimension.

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ISSUE	1	2					Title: Package Outline Drawing for 28 Ids SOIC(W)-0.300" Body Width (MP)
ACN	006746	201943				SEMICONDUCTOR	28 Ids SOIC(W)-0.300 Body Width (MP)
DATE	7APR95	27FEB97					Drawing Number
APPROVED							GPD0001/



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